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SOT-23 ª « ¬ MOS - ® ¯ ° ±

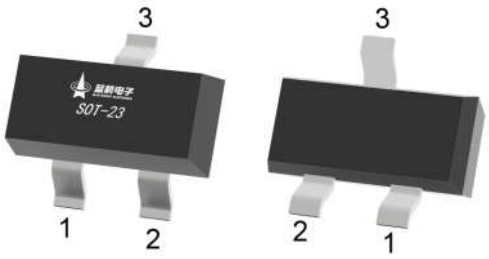
P- CHANNEL MOSFET in a SOT-23 Plastic Package.

² ³ ´ µ MOSFET ¶ · ¸ ¹ º » ¼ ½ ¾ » ¿ ++

Trench Power MOSFET technology, Low $R_{DS(ON)}$,Low Gate Charge, HF Product.

À Á Â Ã Ä Å Æ ±

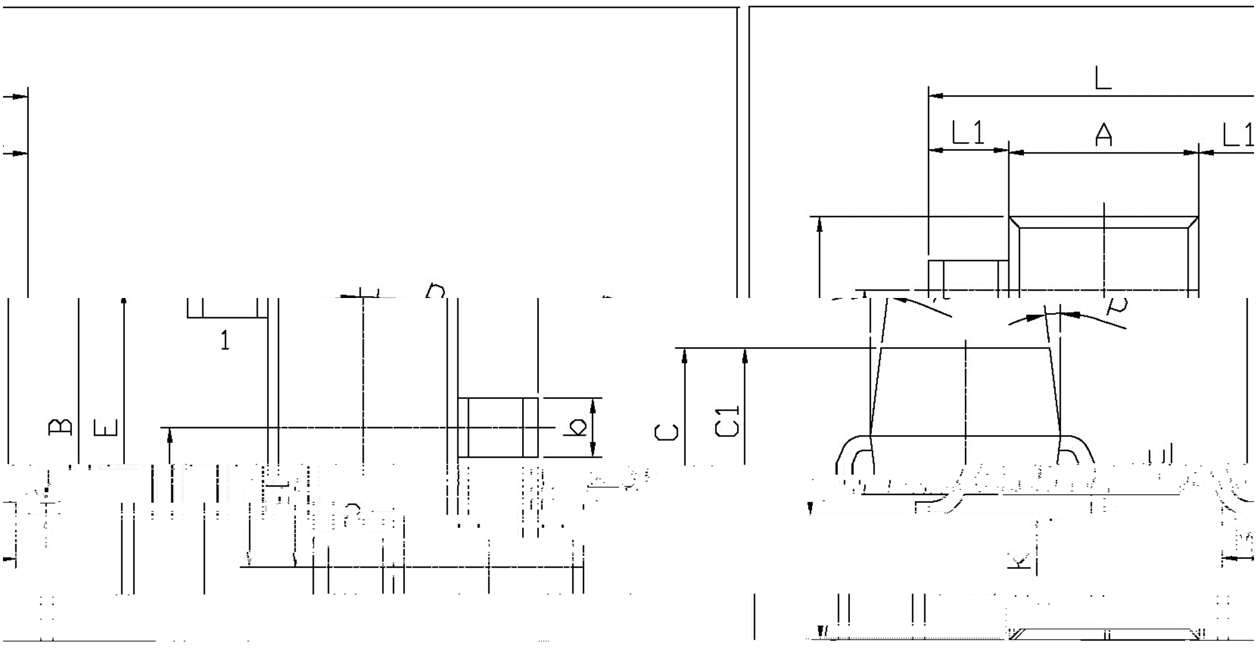
Primarily the display screen drive applications.



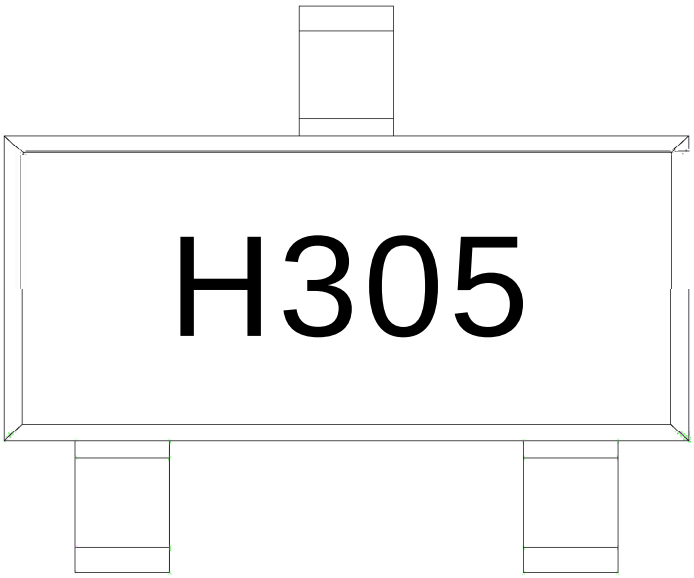
PIN1 Ç G PIN 2 Ç S PIN 3 Ç D

Parameter	È É Symbol	Î Ï Ð Ñ Test Conditions	ÒÓÊ Min	ÔÕÊ Typ

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Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	1.30Max		L	2.2	2.7
C1	0.90	1.20	L1	0.45	0.65
c	0.05	0.20	A	1.15	1.50
[illegible]	0	[illegible]	[illegible]	[illegible]	[illegible]
[illegible]	[illegible]	[illegible]	[illegible]	[illegible]	[illegible]
			o	0.35	0.55



× Ø Ç

H: Ù Ú Û

305: Õ É Û

Note:

H: Company Code.

305 Ç Product Type

Temperature Profile for IR Reflow Soldering(Pb-Free)



× Ø Ç

1 Ü Ý Þ ß à 150 á 180 Í â ã 60 á 90sec;

2 Ü ä Ê ß à 245å5 Í â ã æ ç 5å0.5sec;

3 Ü è é ê ë ì à 2 á 10 Í /sec.

Note:

1.Preheating:150~180 Í , Time:60~90sec.

2.Peak Temp.:245å5 Í , Duration:5å0.5sec.

3. Cooling Speed: 2~10 Í /sec.

ß à Ç 260å5 Í â ã Ç 10å1 sec.

Temp.:260å5 Í Time:10å1 sec

í î ï / REEL

Package Type	Units	Dimension (unit mm³)
	Units/Re	